

Date:04/16/21

Attendees: Denis, Anthony, Ali, Allan, Craig, David, Denis, Eelco, Giridhar, Gus, Halil, Liz, Hesham, Letizia, Michael, Mudasir, Myron, Nick, Peter, Quinn, Reza, Rob, Sam, Scott, Steven, Suresh, Swami, Tawfik, Timothy, Bapi

<https://global.gotomeeting.com/join/950275429>

1. Rolling Agenda:
 - a. 4/16: LETI
 - b. 4/23: Sehat @ FLC Technology
 - c. 4/30: CPO - Rob @ FB and Shahab @ Ayar
2. Agenda:
 - a. LETI/LIST
 - i. Denis and Anthony
 - ii. Focus on domain-specific active interposers
 - iii. Discussion on latency and ESD (Peter)
 - iv. Need an open D2D link standard. Perhaps CXL data layer.
 - v. Allan - OMI is an option
3. Opens
 - a.
4. Announcement
 - a.
5. Weekly workstream minutes
 - a. BoW - <https://github.com/opencomputeproject/ODSA-BoW/issues/38>:
 - i.
 - b. CDX - https://docs.google.com/document/d/1ZVA1_qMWSdIhjHBF21pwucmy9LqAID8fQwpog8Vcxl/edit?usp=sharing
 - c. Link Layer - https://docs.google.com/document/d/1vlbfsgkG4ef8Sqs1IBb1_tvIjl-ffJS0T8-PnESxTk/edit?usp=sharing
 - i.
 - d. PIPE - https://docs.google.com/document/d/1g9m6FdBaWzHj8BIRI5ADlbJVT-GR_8ODVaxHTg5Snw0/edit?usp=sharing
 - i.
 - e. PoC HW <https://docs.google.com/document/d/1UOdbOrF2TG7zZQCadLFZ1ujljAkl3FXra5wGJ-QkZ1o/edit?usp=sharing>
 - i.

- f. PoC SW -
<https://docs.google.com/document/d/1kpgZL1mH-sMOdA0wWFOcnNLoctSZdo68jw-UEVcqLZo/edit?usp=sharing>
 - i. Working on remote access
 - g. Open HBI - contact Kenneth Ma
 - h. Business workflow
 - i.
6. Speaker ideas
- a. HBM Thermal Management
 - b. Quality and Reliability - ESD, aging, electromigration - Bill HIR workgroup, ANSYS, packaging reliability - thermal effects, mechanical - as applies to chiplets
 - c. Anyone making chiplets - commercial talks focused on chiplets
 - d. Memory access discussion - HBM, GenZ, OMI - how do they become compatible with chiplets - WD/Micron/IBM/Samsung/SK/Seagate - new protocol? Sequence of memory-focused talks - Allan - October
 - e. Prof. Flynn from Michigan
 - f. DARPA official CHIPS - Eelco - October/November
 - g. CHIPS - Andreas - October
 - h. TSMC - Bill, Suresh
 - i. Transaction Protocol for D2D review
 - j. Bit errors in substrates
 - k. End user workgroup - DJ
 - l. Any other foundry (Global) or AMAT?
 - m. Ken, Open HBI in February
 - n. Quinn in February - Software
 - o. Someone @ ARM in Q1
 - p. Bill@IEEE in March for the HIR
 - q. Allan - Modular design for mini OAM, bare die on the module
 - r. Sam will come up with something
 - s. Ali - top-level architecture - modular design
 - t. Philippe@Boyd - thermal management
 - u. Nhat@Rambus - check on internal talks, cover the ISSCC talk
 - v. Shahab@ISSCC talks - chase them down
 - w. Ravi - disaggregation of SRAM, persistent memory,
 - x. DJ@End User in Feb
 - y. Jawad - How do we use existing chips as chiplets - panel. How do we define a chiplet, isn't this MCM packaging? What's different? What is the current MCM biz model, state of flow. How do understand the die sales model and its relevance for chiplets. Can we use the PoC as a starting point + Ali
 - z. Ali@Mature process nodes
 - aa. Get panelists to do longer talks.
 - bb. OAM expert to do a talk

